

Description

Designed to protect voltage sensitive electronic components from ESD and other transients. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

The combination of small size, low capacitance, and high level of ESD protection makes them a flexible solution for applications such as HDMI, Display Port TM, and MDDI interfaces. It is designed to replace multiplayer varistors (MLV) in consumer equipments applications such as mobile phone, notebook, PAD, STB, LCD TV etc.

Features

Bi-directional ESD protection of one line

Reverse stand-off voltage: 5V

Low reverse clamping voltage

Low leakage current

Fast response time

IEC 61000-4-2 (ESD) immunity test :

Air discharge: $\pm 30\text{kV}$

Contact discharge: $\pm 30\text{kV}$

Applications

Computers and peripherals

High speed data lines

Audio and video equipment

Cellular handsets and accessories

Subscriber identity module(SIM) card protection

Portable electronics

FireWire

Other electronics equipments communi- cation systems

5B

SOD-523



Absolute Maximum Rating

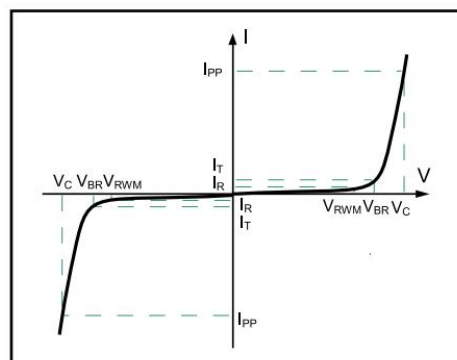
Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	80	W
Peak Pulse Current (8/20 μs)	IPP	8	A
ESD per IEC 61000-4-2 (Air)	VESD	± 30	kV
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	TJ	-55to +125	$^{\circ}\text{C}$
Storage Temperature Range	Tstg	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics

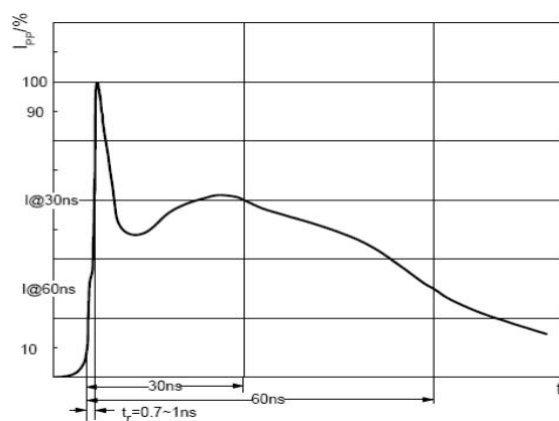
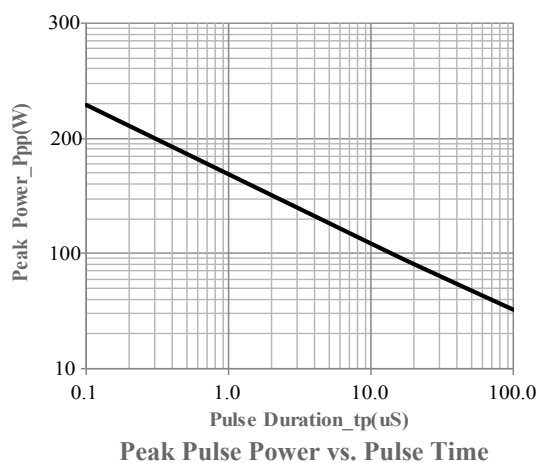
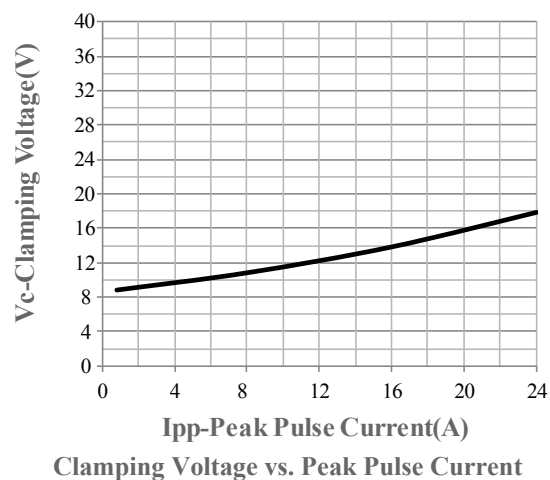
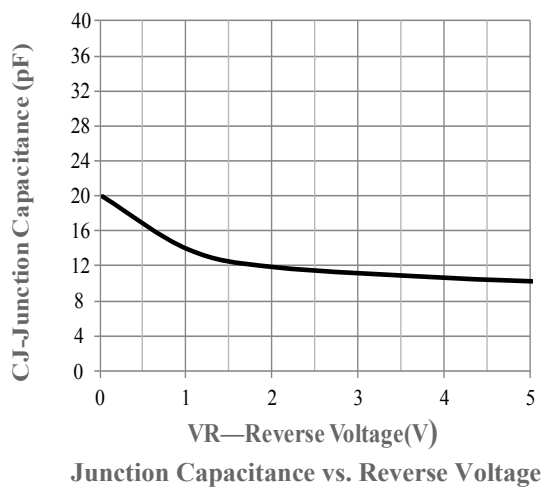
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}				5	V
Breakdown Voltage	V_B	$I_T = 1\text{mA}$	5.6		8	V
Reverse Leakage Current	I_R	$V_{RWM} = \pm 3.3\text{V}$			0.1	μA
Clamping Voltage	V_C	$I_{PP} = 8\text{A}$ (8 x 20 μs pulse)			11	V
Junction Capacitance	C_j	$V_R = 0\text{V}$, $f = 1\text{MHz}$			20	pF

Electronics Parameter

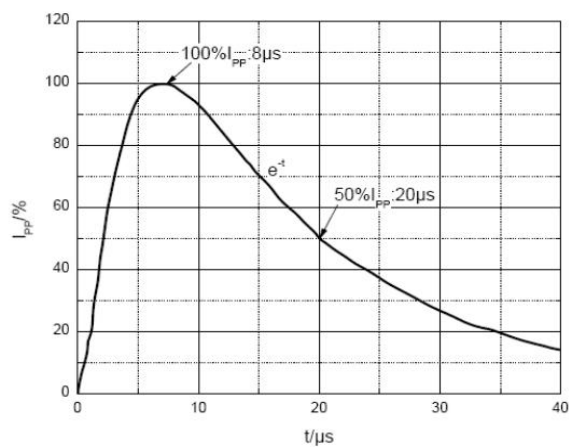
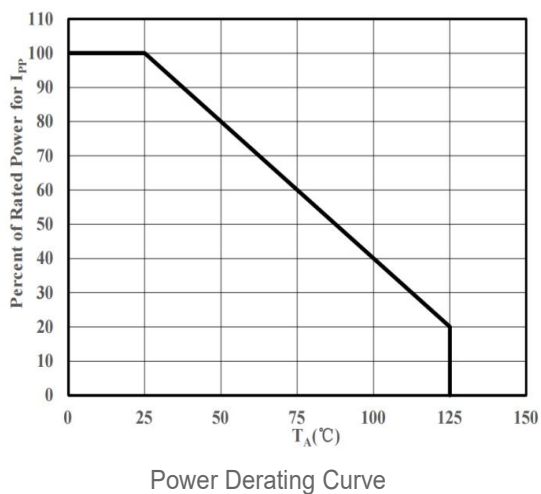
Symbol	Parameter
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_C
V_{BR}	Breakdown Voltage @ I_T
I_R	Reverse Leakage Current @ V_{RWM}
V_{RWM}	Reverse Standoff Voltage



RATING AND CHARACTERISTIC CURVES



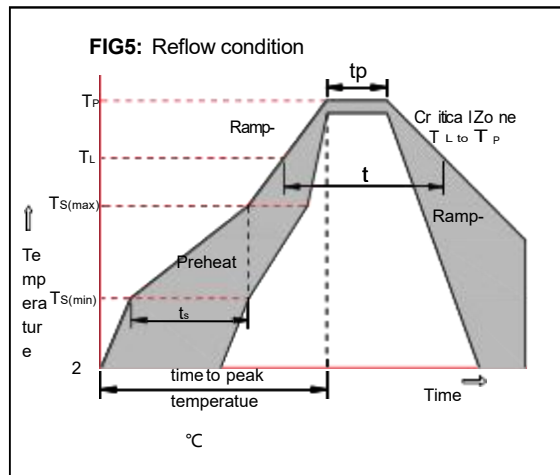
ESD pulse waveform according to IEC61000-4-2



8/20μs pulse waveform according to IEC 61000-4-5

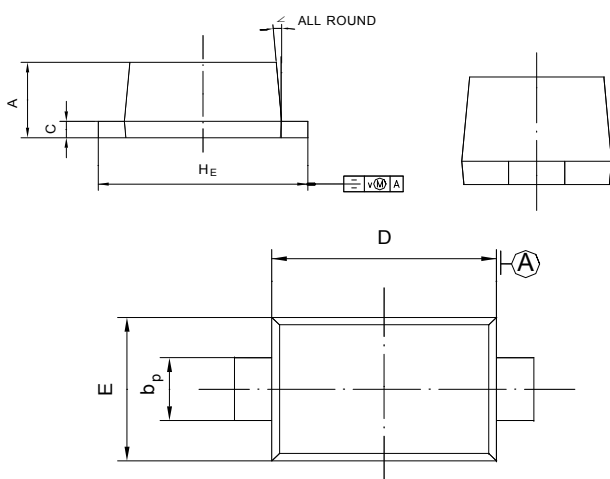
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max ($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature (T_L) (Liquid us)	+217 °C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

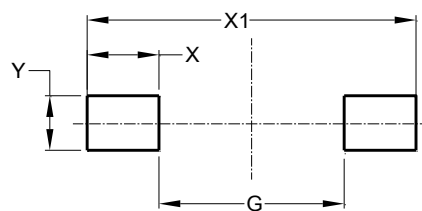


Package Dimensions & Suggested Pad Layout

SOD523

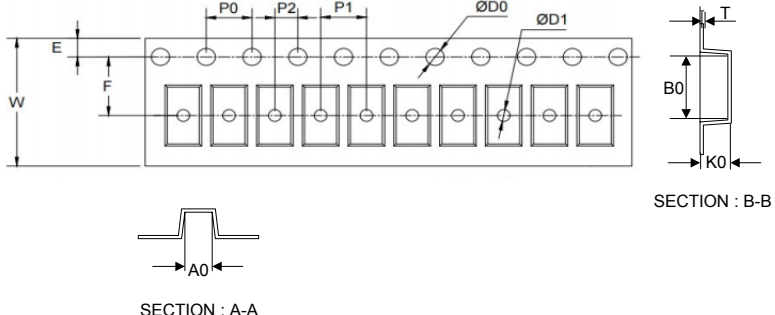
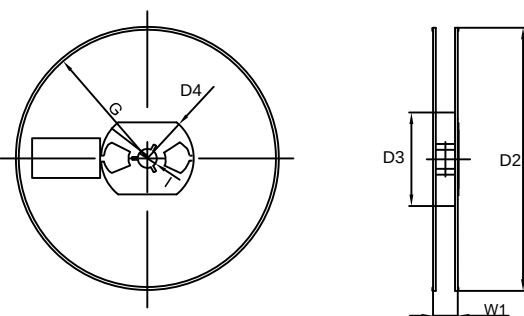


UNIT	A	b _P	C	D	E	H _E	V	∠
mm	0.70 0.50	0.40 0.20	0.14 0.05	1.30 1.10	0.90 0.75	1.70 1.50	0.1	5°



Dimensions	Value (in mm)
G	0.85
X	0.70
X1	2.25
Y	0.80

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	2.00±0.20
		P2	2.00±0.20
		D0	1.55±0.20
		D1	0.50±0.20
		E	1.55±0.25
		F	3.60±0.20
		W	8.00±0.20
		A0	1.30±0.20
		B0	2.35±0.20
		K0	0.95±0.20
		T	0.20±0.20
		D2	177.0±5.0
		D3	55Min.
7" Reel		D4	R24.6±2.0
		G	R82.0±2.0
		I	13.0±2.0
		W1	10.20±3.0
		Quantity: 3000PCS	